

## 10 G BASE-T MAGNETICS MODULES MODEL NO.: XF-GH-002

### FEATURE:

RoHS Compliant

RoHS peak solder rating 260°C/ 3~5 Sec

Do not use material and use that the prohibition that SS-00259 stipulates

Designed to meet IR requirement

Compliant with IEEE 802.3 standard

Qualified with top 10G PHY Manufacturers

Low profile package for PCI Express

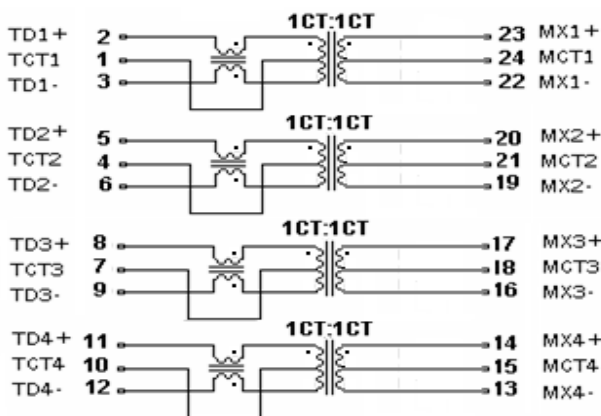
Fine-tuned magnetics to specific PHY vendors

Operating temp. : 0°C TO +80°C

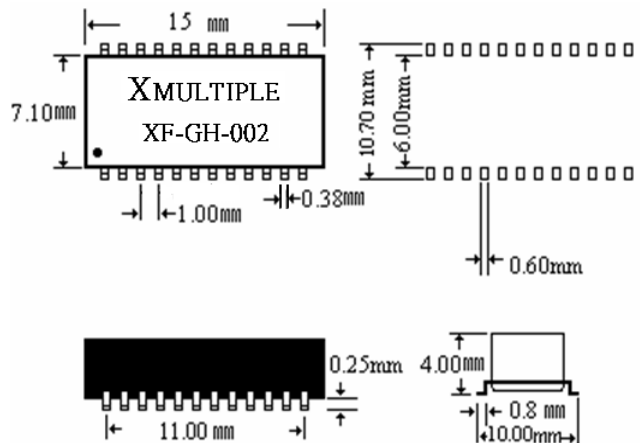
Specifications @ 25°C

Insertion Loss (dB MAX)	Return Loss (dB Min @100Ω)		Common Mode Rejection Ratio (dB MIN)		Cross talk (dB MIN)		Hipot Vrms Min.
	1~500 MHz	1~40 MHz	40~500 MHz	1~250 MHz	250~500 MHz	1~100 MHz	
-2.5	-18	-17+10*LOG (f/40)	-30	-22	-40	-30	1500

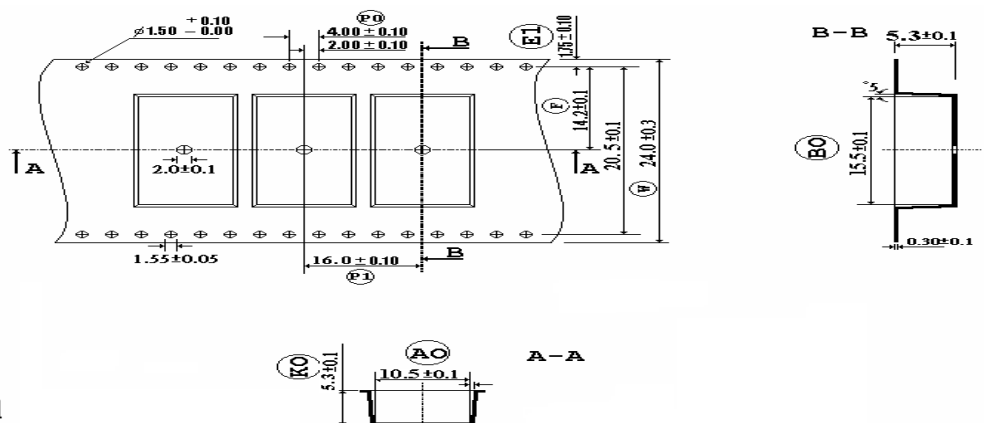
### SCHEMATICS:



### DIMENSION: mm TOLERANCE:±0.25



### Packing :



W: 24.0±0.30  
P1: 16.0±0.10  
AO: 10.5±0.10  
BO: 15.5±0.10  
KO: 5.30±0.10  
Tape & reel-----800/reel

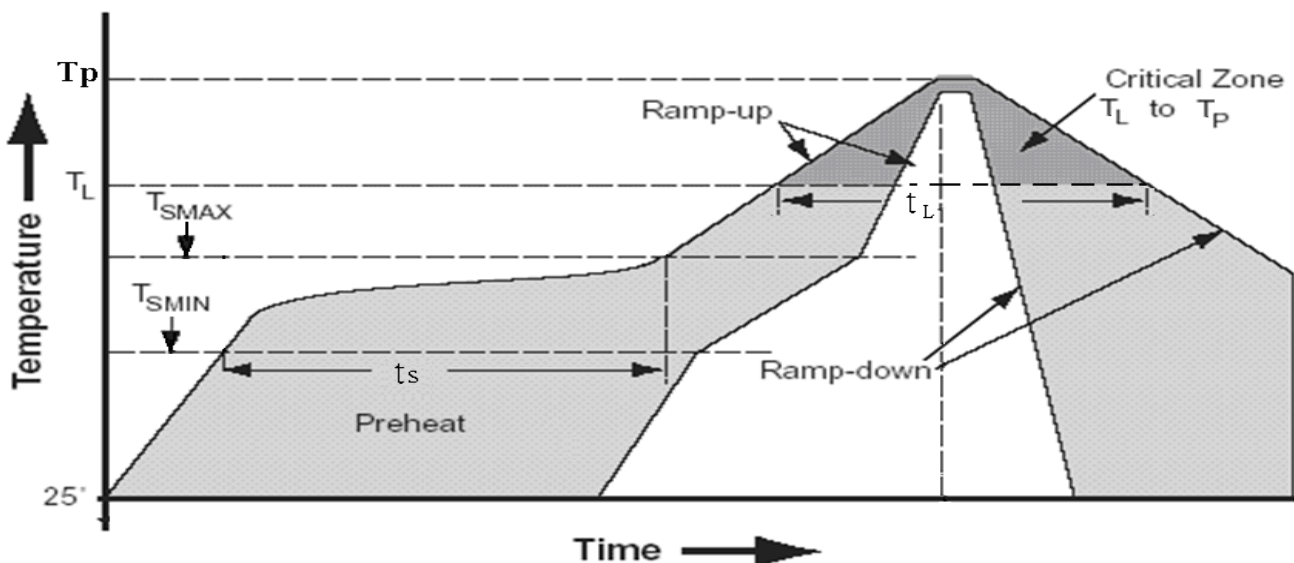
## MODEL NO.: XF-GH-002

Solder Reflow profile for Lead-Free packages.  
Package Peak Reflow Temperatures

### Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate( $T_L$ to $T_P$ )	3°C / Second Max.	
Preheat		
Temperature Min.( $T_s$ min.)	150 °C	
Temperature Max.( $T_s$ max.)	200 °C	
Time (min to max) ( $t_s$ )	60-180 sec	
$T_s$ max. to $T_L$ Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature ( $T_L$ ) Time ( $t_L$ )	217 °C 60-150 sec	
Peak Temperature ( $T_p$ )	260 +0 / -5 °C	250 +0 / -5 °C
Time within 5 °C of actual peak Temp.	3 to 5 Sec	20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

### Profile



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### PACKING

1. Tape & Reel : 800pcs / Reel , 4000pcs / Carton
2. Dry Pack : 1pcs  
Product Description:(5g Silica Gel Desiccant)  
PH: 4-8  
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum
4. Seal Per JEDEC

